

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-38 (cancelled).

39. (withdrawn) A semiconductor device comprising:
a sealing member formed of an insulating resin;
a semiconductor element sealed by the sealing member;
a plurality of terminals formed by a metal film and
exposed to a back surface of the sealing member; and

conductive wires positioned within the sealing member,
ends on one side of the conductive wires being connected
respectively to electrodes formed over the semiconductor
element and opposite ends thereof being connected
respectively to the terminals,

wherein the plural terminals are arrayed in plural
rows and plural columns around the semiconductor element,
and

wherein a back surface of the semiconductor element,
back surfaces of the terminals and the back surface of the
sealing member lie over one and same plane, and the back

surface of the semiconductor element and the back surfaces of the terminals are exposed from the sealing member.

40. (withdrawn) A semiconductor device comprising:
a sealing member formed of an insulating resin;
a semiconductor element sealed by the sealing member:
a plurality of terminals formed by a metal film and exposed to a back surface of the sealing member; and
conductive wires positioned within the sealing member, ends on one side of the conductive wires being connected respectively to electrodes formed over the semiconductor element and opposite ends thereof being connected respectively to the terminals,

wherein the plural terminals are arrayed in plural rows and plural columns around the semiconductor element,

wherein an insulating adhesive is provided over the back surface of the semiconductor element, a back surface of the adhesive, the back surfaces of the terminals and the back surface of the sealing member lie over one and same plane, and the back surface of the adhesive and the back surfaces of the terminals are exposed from the sealing member.

41. (withdrawn) A semiconductor device according to claim 40, wherein the adhesive is an adhesive tape.

42. (withdrawn) A semiconductor device comprising:
a sealing member formed of an insulating resin;
a semiconductor element sealed by the sealing member;
a plurality of terminals formed by a metal film and exposed to a back surface of the sealing member; and
conductive wires positioned within the sealing member, ends on one side of the conductive wires being connected respectively to electrodes formed over the semiconductor element and opposite ends thereof being connected respectively to the terminals,

wherein the plural terminals are arrayed in plural rows and plural columns around the semiconductor element, and

wherein the terminals each comprise a main metal layer and one or plural auxiliary metal layers formed over a main surface of the main metal layer or over both the main surface and a back surface of the main metal layer.

43. (withdrawn) A semiconductor device comprising:
a sealing member formed of an insulating resin;

a semiconductor element sealed by the sealing member;
a plurality of terminals formed by a metal film and exposed to a back surface of the sealing member; and
conductive wires positioned within the sealing member, ends on one side of the conductive wires being connected respectively to electrodes formed over the semiconductor element and opposite ends thereof being connected respectively to the terminals,

wherein the plural terminals are arrayed in plural rows and plural columns around the semiconductor element, and

wherein the terminals each comprise a main metal layer and one or plural auxiliary metal layers formed over a main surface of the main metal layer or over both the main surface and a back surface of the main metal layer, one of the auxiliary metal layers formed over the main surface of the main metal layer having a rough surface to provide a rough surface of each of the terminals.

44. (withdrawn) A semiconductor device comprising:
a sealing member formed of an insulating resin;
a semiconductor element sealed by the sealing member;

a plurality of terminals formed by a metal film and exposed to a back surface of the sealing member; and

conductive wires positioned within the sealing member, ends on one side of the conductive wires being connected respectively to electrodes formed over the semiconductor element and opposite ends thereof being connected respectively to the terminals,

wherein the plural terminals are arrayed in plural rows and plural columns around the semiconductor element, and

wherein a plurality of semiconductor elements are sealed within the sealing member.

45. (withdrawn) A semiconductor device comprising:
a sealing member formed of an insulating resin;
a semiconductor element sealed by the sealing member;
a plurality of terminals formed by a metal film and exposed to a back surface of the sealing member; and
conductive wires positioned within the sealing member, ends on one side of the conductive wires being connected respectively to electrodes formed over the semiconductor element and opposite ends thereof being connected respectively to the terminals,

wherein the plural terminals are arrayed in plural rows and plural columns around the semiconductor element, and

wherein a plurality of semiconductor elements are sealed within the sealing member, and at least a portion(s) of the semiconductor elements is (are) fixed superimposedly over the other semiconductor element(s).

46. (withdrawn) A semiconductor device comprising:
a sealing member formed of an insulating resin;
a semiconductor element sealed by the sealing member;
a plurality of terminals formed by a metal film and exposed to a back surface of the sealing member; and
conductive wires positioned within the sealing member, ends on one side of the conductive wires being connected respectively to electrodes formed over the semiconductor element and opposite ends thereof being connected respectively to the terminals,

wherein the plural terminals are arrayed in plural rows and plural columns around the semiconductor element,

wherein a peelable, flexible tape is affixed to the back surface of the sealing member, and

wherein the tape is a band-like tape, the sealing member is formed at predetermined intervals in a longitudinal direction of the tape, and the tape is wound round a reel.

Claims 47-57. (cancelled).

58. (new) A method of manufacturing a semiconductor device, comprising the steps of:

(a) providing a tape having a main surface, a back surface opposed to the main surface, a product forming portion formed on the main surface, and a plurality of terminals formed in the product forming portion;

(b) fixing a semiconductor element to the main surface of the tape;

(c) electrically connecting a plurality of electrodes formed over the semiconductor element with the plurality of terminals through wires, respectively;

(d) sealing the semiconductor element, the wires, the plurality of terminals and the main surface of the tape with a resin, and forming a sealing member;

(e) after the step (d), peeling the tape from the sealing member, and thereby exposing a part of each of the plurality of terminals from the sealing member; and

(f) forming a metal layer over the part of each of the plurality of terminals,

wherein there is no exposure of the plurality of terminals and terminal leads from edges of the sealing member; and

wherein the metal layer is formed by a printing process.

59. (new) The method according to claim 58, wherein the plurality of terminals are formed by affixing a metal foil to the main surface of the tape and thereafter etching the metal foil selectively.

60. (new) The method according to claim 59, wherein the metal foil is affixed to the main surface of the tape through a first adhesive.

61. (new) The method according to claim 59, wherein the metal foil is compression-bonded to the tape by thermocompression bonding.

62. (new) The method according to claim 58, wherein a back surface of the semiconductor element is exposed from the sealing member.

63. (new) The method according to claim 58, wherein the tape has a semiconductor element fixing piece, and the semiconductor element is mounted over the semiconductor element fixing piece.

64. (new) The method according to claim 58, wherein the plurality of terminals are fixed to the tape through a first adhesive, and the semiconductor element is fixed to the tape through a second adhesive.

65. (new) The method according to claim 59, wherein a Pd plating film is formed over each of the plurality of terminals.

66. (new) The method according to claim 58, wherein the tape is formed by a resin film selected from polyimide resin, ethylene-vinylacetate copolymer resin, polyolefin resin and methacrylate resin.

67. (new) The method according to claim 58, wherein the step (d) is carried out while the back surface of the tape is held by vacuum suction.